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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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RF and MICROWAVE DISCRETE LOW POWER TRANSISTORS

Qualified per MIL-PRF-19500/343

Qualified Levels: JAN, JANTX, and JANTXV

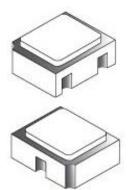
DESCRIPTION

The 2N2857UB is a military qualified silicon NPN transistor (also available in commercial version), designed for UHF equipment and other high-reliability applications. Common applications include low noise amplifier; oscillator, and mixer applications. Microsemi also offers numerous other products to meet higher and lower power voltage regulation applications.

Important: For the latest information, visit our website http://www.microsemi.com.

FEATURES

- Surface mount equivalent to JEDEC registered 2N2857.
- Silicon NPN, UB packaged UHF transistor.
- Maximum unilateral gain = 13 dB (typ) @ 500 MHz.
- JAN, JANTX, and JANTXV military qualified versions available per MIL-PRF-19500/343.
- RoHS compliant version available (commercial grade only).



UB Package

Also available in:



梵 TO-72 Package (axial-leaded) 2N2857

APPLICATIONS / BENEFITS

- Low-power, ultra-high frequency transistor.
- Low-profile ceramic surface mount package.

MAXIMUM RATINGS \bigcirc T_A = +25 $^{\circ}$ C

Parameters/Test Conditions	Symbol	Value	Unit	
Junction and Storage Temperature	T_J and T_{STG}	-65 to +200	°C	
Collector-Emitter Voltage	V _{CEO}	15	V	
Collector-Base Voltage	V_{CBO}	30	V	
Emitter-Base Voltage	V_{EBO}	3	V	
Thermal Resistance Junction-to-Ambient	R _{OJA}	400	°C/W	
Thermal Resistance Junction-to-Solder Pad	R _{OJSP}	210	°C/W	
Steady-State Power Dissipation (1)	P _D	200	mW	
Collector Current	Ic	40	mA	

Notes: 1. Derate linearly 1.14 mW/°C for $T_A > +25$ °C.

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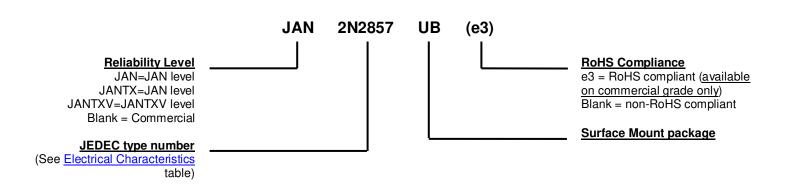
www.microsemi.com



MECHANICAL and PACKAGING

- CASE: Ceramic.
- TERMINALS: Gold plating over nickel underplate. RoHS compliant matte/tin available on commercial grade only.
- MARKING: Part number, date code, manufacturer's ID.
- TAPE & REEL option: Standard per EIA-418D. Consult factory for quantities.
- WEIGHT: < 0.04 Grams.
- See Package Dimensions on last page.

PART NOMENCLATURE



	SYMBOLS & DEFINITIONS						
Symbol	Definition						
Ic	Collector current (dc).						
I _B	Base current (dc).						
T _A	Ambient or free air temperature.						
T _C	Case temperature.						
V _{CB}	Collector to base voltage (dc).						
V _{EB}	Emitter to base voltage (dc).						



ELECTRICAL CHARACTERISTICS @ T_C = +25 °C

OFF CHARACTERISTICS

Took Conditions	Cumbal	Value				
Test Conditions	Symbol	Min. Typ.		Max.	Unit	
Collector-Emitter Breakdown Voltage ($I_C = 3.0 \text{ mA}$, Bias condition D)	V _{(BR)CEO}	15	-	-	٧	
Collector to Emitter Cutoff Current (V _{CE} = 16 V, Bias condition C)	I _{CES}	-	-	100	nA	
Emitter to Base Cutoff Current (V _{EB} = 3 V, Bias condition D)	I _{EBO}	-	-	10	μА	
Collector to Base Cutoff Current (V _{CB} = 15 V, Bias condition D)	I _{CBO}	-	-	10	nA	

ON CHARACTERISTICS

-					
Test Conditions	Symbol	Min.	Тур.	Max.	Unit
Forward Current transfer ratio (I _C = 3.0 mA, V _{CE} = 1.0 V)	h _{FE}	30	-	150	
Collector-Emitter Saturation Voltage ($I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$)	V _{CE(sat)}		-	0.4	٧
Base-Emitter Saturation Voltage (I _C = 10 mA, I _B = 1 mA)	V _{BE(sat)}		-	1.0	V

DYNAMIC CHARACTERISTICS

Test Conditions	Cumbal		l lmia			
rest Conditions	Symbol	Min.	Тур.	Max.	Unit	
Magnitude of common emitter small signal short circuit forward current transfer ratio $(V_{CE}=6\ V,\ Ic=5\ mA,\ f=100\ MHz)$	h _{fe}	10	-	21		
Collector-base time constant ($I_E = 2.0$ mA, $V_{CB} = 6.0$ V, $f = 31.9$ MHz)	r _b 'C _c	4	-	15	pF	
Collector to Base – feedback capacitance ($I_E = 0$ mA, $V_{CB} = 10$ V, 100 kHz $\leq f \leq 1$ MHz	C _{cb}			1.0	pF	
Noise Figure (50 Ohms) (I _C = 1.5 mA, V_{CE} = 6 V, f = 450 MHz, R_g = 50 Ω)	F		4.5		dB	
Small Signal Power Gain (common emitter) (I _E = 1.5 mA, V _{CE} = 6 V, f = 450 MHz	G _{pe}	12.5		21	dB	



GRAPHS

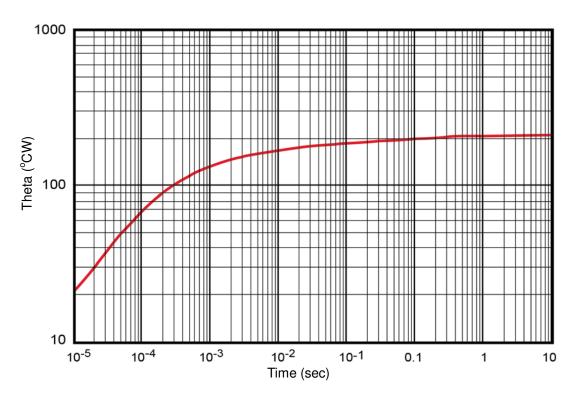
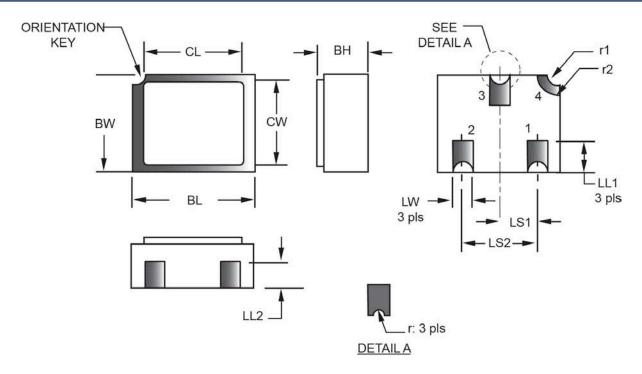


FIGURE 1

Maximum Thermal Impedance



PACKAGE DIMENSIONS



	Dime	ensions				Dimensions					
Symbol inch		millimeters		Note	Symbol	inch		millimeters		Note	
	Min	Max	Min	Max			Min	Max	Min	Max	
BH	.046	.056	1.17	1.42		LS1	.035	.039	0.89	1.02	
BL	.115	.128	2.92	3.25		LS2	.071	.079	1.80	2.01	
BW	.085	.108	2.16	2.74		LW	0.16	0.24	0.41	0.61	
CL		.128		3.25		r		.008		0.20	
CW		.108		2.74		r1		.012		0.31	
LL1	.022	.038	0.56	0.97		r2		.022		.056	
LL2	.017	.035	0.43	0.89							

NOTES:

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Hatched areas on package denote metallized areas.
- 4. Pad 1 = Base, Pad 2 = Emitter, Pad 3 = Collector, Pad 4 = Shielding connected to the lid.
- 5. In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.